

RF TECHNOLOGY OVERVIEW

Product Type - Characteristics

Mixed Dielectrics for RF & Digital

Buried / Blind / Microvia Interconnects

Exposed Cavities - Multi Depth

Sequential Lamination

Formed PCB's

Ormet Interconnections

Back Drilling – Via Stub Reduction

Hole Fill - Low DK / Low Loss

Metal Core & Metal Back

Planar Resistors - Ohmega + Ticer

Screened Ink Resistors



Ormet Paste Interconnections



Via Fencing and Edge Plating for EMI Suppression



Stacked Microvias

RF Related Processes

Sodium Etch

Plasma Helium

Autoclave

Fusion Bond

Hydroscan

Specialty Hole Fill

Laser Direct Imaging

Laser Drilling

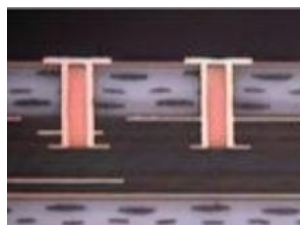
Front to Back Scope

Optical Drill / Mill

ENEPIG, ENIG, Soft Au

RF Test - Vector Network Analyzer (VNA)

RF Assembly



Blind Vias Hybrid - Mixed Dielectrics

TYPICAL RF MATERIAL & PROPERTIES

Material	Dk	Loss (Df)	Typical Freq	Cost Factor	Description
370HR	4.30	0.0250	less than 1 Ghz	1.00	Epoxy woven glass
Taconic TLY	2.20	0.0009	Up to 70 Ghz	7.00	Teflon- woven glass reinforced
Taconic RF35	3.50	0.0025	Up to 10 Ghz	6.00	Teflon-ceramic filled, woven glass reinforced
Arlon CLTE	2.94	0.0024	Up to 20 Ghz	8.00	Teflon-ceramic filled, woven glass reinforced
Arlon CLTE-XT	2.94	0.0012	Up to 40 Ghz	10.00	Teflon-ceramic filled, woven glass reinforced
Rogers 3003	3.00	0.0013	Up to 20 Ghz	8.00	Teflon-ceramic filled
Rogers 3203	3.02	0.0016	Up to 20 Ghz	8.00	Teflon-ceramic filled, woven glass reinforced
Rogers 4350	3.48	0.0040	Up to 10 Ghz	5.00	Ceramic filled hydrocarbon, woven glass reinforced
Rogers 5880	2.20	0.0009	Up to 100 Ghz	20.00	Teflon-random glass reinforced
Rogers 6002	2.94	0.0012	Up to 40 Ghz	25.00	Teflon-ceramic filled
Rogers 6202	2.94	0.0013	Up to 40 Ghz	1 5.00	Teflon-ceramic filled, woven glass reinforced
Rogers 6010	10.20	0.0020	Up to 20 Ghz	30.00	Teflon-ceramic filled

DESIGN FOR MANUFACTURING GUIDELINES FOR RF PRODUCTS

CRITICAL ATTRIBUTE			CRITICAL ATTRIBUTE		
Feature to Feature Criteria	Standard	Advanced	Mechanical Process Related Criteria	Standard	Advanced
Line Width / Space (inner layers)			General		
.5 oz copper	.0045" min. /.004" min.	.004" min. /.0035" min.	Rout edge to ground plane	.025" min.	.015" min.
1 oz copper	.005" min. /.0045" min.	.005" min. /.004" min.	Routed hole tolerance	+/- .005	+/- .003"
2 oz copper	.0065" min. /.005" min.	.006" min. /.005" min.	Inside radius	.047"	.032"
Line Width / Space (outer layers)			Edge of cavity to nearest thru hole	.030" min.	.020" min.
1 oz copper	.005" min. /.0045" min.	.005" min. /.004" min.	Rout to imaged feature tolerance	+/- .007"	+/- .003"
2 oz copper	.0065" min. /.005" min.	.006" min. /.005" min.	Outside dimension tolerance	+/- .007"	+/- .005"
			Controlled depth rout / mill	.007" min.	.005" min.
			Backdrill stub length	+/- .005"	+/- .003"
			PTH drill to copper feature	.015" min.	.010" min.
			NPTH drill to copper feature	.015" min.	.010" min.
			Drill to board edge	.020" min.	.0135" min.
			Finished PTH size tolerance	+/- .003"	+/- .002"
			Non-PTH size tolerance	+/- .002"	+/- .001"
			Drill true position (DTP)	.008 (RMC)	.006" (RMC)
Hole Related Criteria					
Annular Ring (inner layers)					
			Class II tangency	Class III .001"	Class II tangency Class III .001"
One lamination					
Pad dia. for .5 oz copper	Drill + .014"	Drill + .016"	Drill + .012"	Drill + .014"	
Pad dia. for 1 oz copper	Drill + .014"	Drill + .016"	Drill + .012"	Drill + .016"	
Pad dia. for 2 oz copper	Drill + .016"	Drill + .018"	Drill + .014"	Drill + .016"	
Two laminations					
Pad dia. for .5 oz copper	Drill + .016"	Drill + .018"	Drill + .014"	Drill + .016"	
Pad dia. for 1 oz copper	Drill + .016"	Drill + .018"	Drill + .014"	Drill + .016"	
Pad dia. for 2 oz copper	Drill + .018"	Drill + .020"	Drill + .016"	Drill + .018"	
Three laminations					
Pad dia. for .5 oz copper	Drill + .018"	Drill + .020"	Drill + .016"	Drill + .018"	
Pad dia. for 1 oz copper	Drill + .018"	Drill + .020"	Drill + .016"	Drill + .018"	
Pad dia. for 2 oz copper	Drill + .020"	Drill + .022"	Drill + .018"	Drill + .020"	